



Material Content Data Sheet



Sales Product Name		BSZ0909NS		Issued		29. August 2013		
MA#		MA000891618						
Package		PG-TSDSON-8-1		Weight*		36.63 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.531	1.45	1.45	14490	14490
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65	
	non noble metal	zinc	7440-66-6	0.009	0.03		258	
	non noble metal	iron	7439-89-6	0.189	0.52		5170	
wire	non noble metal	copper	7440-50-8	7.689	20.99	21.55	209919	215412
	non noble metal	copper	7440-50-8	0.039	0.11	0.11	1074	1074
	encapsulation	organic material	carbon black	1333-86-4	0.039	0.11		1075
leadfinish	plastics	epoxy resin	-	2.027	5.53		55347	
	inorganic material	silicondioxide	60676-86-0	17.615	48.08	53.72	480924	537346
	non noble metal	tin	7440-31-5	0.370	1.01	1.01	10104	10104
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2206	2206
solder	non noble metal	tin	7440-31-5	0.017	0.05		466	
	noble metal	silver	7440-22-4	0.021	0.06		583	
	non noble metal	lead	7439-92-1	0.816	2.23	2.34	22271	23320
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.001	0.00		27	
	non noble metal	zinc	7440-66-6	0.004	0.01		107	
	non noble metal	iron	7439-89-6	0.078	0.21		2139	
	non noble metal	copper	7440-50-8	3.182	8.69	8.91	86868	89141
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		32	
	non noble metal	zinc	7440-66-6	0.005	0.01		128	
	non noble metal	iron	7439-89-6	0.094	0.26		2566	
	non noble metal	copper	7440-50-8	3.816	10.42	10.69	104181	106907
*deviation	< 10%		Sum in total:			100,00		1000000

Important Remarks:

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